Filename: ProCA8F.tmp
Variant: 001
Generated: 12/5/2017 5:22:32 PM
TID #: 01491

TIDA-01491 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-01491	Any	Printed Circuit Board	
2	C1	1	10uF	GCM31CC71E106KA03L	MuRata	CAP, CERM, 10 uF, 25 V, +/- 10%, X7S, AEC-Q200 Grade 1, 1206_190	1206_190
3	C2	1	22uF	GCM31CR70J226KE23L	MuRata	CAP, CERM, 22 µF, 6.3 V,+/- 10%, X7R, AEC-Q200 Grade 1, 1206	1206
4	C3, C5	2	4.7uF	GCM21BC71E475KE36L	MuRata	CAP, CERM, 4.7 µF, 25 V,+/- 10%, X7S, AEC-Q200 Grade 1, 0805	0805
5	C4, C6	2	0.1uF	CGA3E2X7R1E104K080AA	TDK	CAP, CERM, 0.1 µF, 25 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603
6	C7, C8, C9, C10	4	10uF	GCM21BR70J106KE22L	MuRata	CAP, CERM, 10 µF, 6.3 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0805	0805
7	C11	1	0.033uF	CGA2B1X7R1E333K050BC	TDK	CAP, CERM, 0.033 uF, 25 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
8	C12, C13	2	0.01uF	CGA2B3X7R1H103K050BB	TDK	CAP, CERM, 0.01 uF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
9	C14	1	68pF	GCM1885C1H680JA16D	MuRata	CAP, CERM, 68 pF, 50 V, +/- 5%, C0G/NP0, AEC-Q200 Grade 1, 0603	0603
10	H1	1		GHR-08V-S	JST	Will add component to BOM. Useful for cables, nuts, etc. not in libraries	Housing receptacle
11	H2, H3, H4, H5, H6, H7, H8, H9	8		SSHL-002T-P0.2	JST	Will add component to BOM. Useful for cables, nuts, etc. not in libraries	Terminal
12	J1	1		59S10H-40ML5-Z	Rosenberger	Connector, HF, 50 Ohm, TH	SMA Connector
13	J2, J3, J4	3		JMP-36-30X40SMT	Any	Jumper, SMT	shorting jumper, SMT
14	J5	1		BM08B-GHS-TBT(LF)(SN)(N)	JST Manufacturing	Header(shrouded), 1.25mm, 8x1, Tin, TH	Header(shrouded), 1.25mm, 8x1, TH
15	L1, L5	2	2.2uH	SRN2010TA-2R2M	Bourns	Inductor, Shielded, Ferrite, 2.2 uH, 1.2 A, 0.174 ohm, AEC-Q200 Grade 1, SMD	2.0x1.6x1.0mm
16	L2, L4, L8	3	1500 ohm	BLM18HE152SN1D	MuRata	Ferrite Bead, 1500 ohm @ 100 MHz, 0.5 A, 0603	0603
17	L3	1	600 ohm	BLM18KG601SN1D	MuRata	Ferrite Bead, 600 ohm @ 100 MHz, 1.3 A, 0603	0603
18	L7	1	10uH	LQH3NPZ100MJRL	MuRata	Inductor, Wirewound, Ferrite, 10 uH, 0.81 A, 0.288 ohm, AEC-Q200 Grade 1, SMD	3x3mm
19	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650 x 0.200 inch
20	R1	1	4.12k	ERA-3AEB4121V	Panasonic	RES, 4.12 k, 0.1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
21	R2	1	11k	CRCW040211K0JNED	Vishay-Dale	RES, 11 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402
22	R3, R5, R9, R11	4	150k	ERJ-2RKF1503X	Panasonic	RES, 150 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0402	0402
23	R4, R7	2	470k	ERJ-2RKF4703X	Panasonic	RES, 470 k, 1%, .1 W, AEC-Q200 Grade 0, 0402	0402
24	R6	1	300k	CRCW0402300KFKED	Vishay-Dale	RES, 300 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402	0402
25	R8	1	698k	ERJ-2RKF6983X	Panasonic	RES, 698 k, 1%, .1 W, AEC-Q200 Grade 0, 0402	0402
26	R10	1	210k	ERJ-2RKF2103X	Panasonic	RES, 210 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0402	0402
27	U1	1		TPS62160QDSGRQ1	Texas Instruments	3V-17V 1A Automotive Step-Down Converters in 2x2SON, DSG0008A (WSON-8)	DSG0008A
28	U2	1		TPS65000TRTERQ1	Texas Instruments	2.25MHz Step-Down Converter with Dual LDOs & SVS Power Management IC (PMIC), RTE0016C (WQFN-16)	RTE0016C
29	FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated (‘TI”) technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, “TI Resources”) are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI’s provision of TI Resources does not expand or otherwise alter TI’s applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED “AS IS” AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI’s standard terms for semiconductor products http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated